SY58607U

3.2Gbps Precision, 1:2 LVPECL Fanout Buffer with Internal Termination and Fail Safe Input

Precision Edge®

General Description

The SY58607U is a 2.5/3.3V, high-speed, fully differential 1:2 LVPECL fanout buffer optimized to provide two identical output copies with less than 20ps of skew and less than 10ps$_{pp}$ total jitter. The SY58607U can process clock signals as fast as 2.5GHz or data patterns up to 3.2Gbps.

The differential input includes Micrel's unique, 3-pin input termination architecture that interfaces to LVPECL, LVDS or CML differential signals, (AC- or DC-coupled) as small as 100mV (200mV$_{pp}$) without any level-shifting or termination resistor networks in the signal path. For AC-coupled input interface applications, an integrated voltage reference (V$_{REF-AC}$) is provided to bias the V$_T$ pin. The outputs are 800mV LVPECL, with extremely fast rise/fall times guaranteed to be less than 110ps.

The SY58607U operates from a 2.5V ±5% supply or 3.3V ±10% supply and is guaranteed over the full industrial temperature range (–40°C to +85°C). For applications that require CML or LVDS outputs, consider the SY58606U and SY58608U, 1:2 fanout buffers with 400mV and 325mV output swings respectively. The SY58607U is part of Micrel's high-speed, Precision Edge® product line.

Datasheets and support documentation can be found on Micrel's web site at: www.micrel.com.

Functional Block Diagram
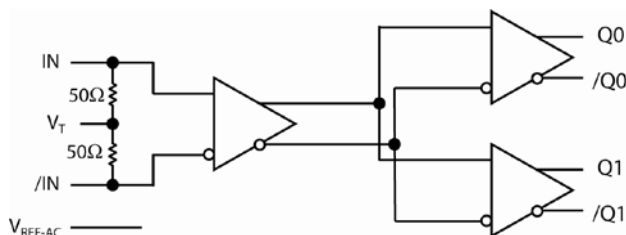
Features

- Precision 1:2, 800mV LVPECL fanout buffer
- Guaranteed AC performance over temperature and voltage:
  - DC-to > 3.2Gbps throughput
  - <350ps propagation delay (IN-to-Q)
  - <20ps within-device skew
  - <110ps rise/fall times
- Fail Safe Input
  - Prevents outputs from oscillating when input is invalid
- Ultra-low jitter design
  - <1ps$_{RMS}$ cycle-to-cycle jitter
  - <10ps$_{PP}$ total jitter
  - <1ps$_{RMS}$ random jitter
  - <10ps$_{PP}$ deterministic jitter
- High-speed LVPECL outputs
- 2.5V ±5% or 3.3V ±10% power supply operation
- Industrial temperature range: –40°C to +85°C
- Available in 16-pin (3mm x 3mm) QFN package

Applications

- All SONET clock and data distribution
- Fibre Channel clock and data distribution
- Gigabit Ethernet clock and data distribution
- Backplane distribution

Markets

- Storage
- ATE
- Test and measurement
- Enterprise networking equipment
- High-end servers
- Access
- Metro area network equipment

Ordering Information[1]

Part Number	Package Type	Operating Range	Package Marking	Lead Finish
SY58607UMG	QFN-16	Industrial	607U with Pb-Free bar-line indicator	NiPdAu Pb-Free
SY58607UMGTR[2]	QFN-16	Industrial	607U with Pb-Free bar-line indicator	NiPdAu Pb-Free

Notes:

1. Contact factory for die availability. Dice are guaranteed at TA = 25°C, DC Electricals only.

2. Tape and Reel.

Pin Configuration
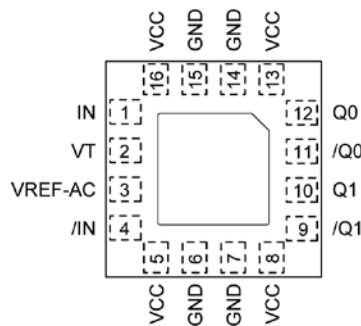
16-Pin QFN

Pin Description

Pin Number	Pin Name	Pin Function
1, 4	IN, /IN	Differential Input: This input pair is the differential signal input to the device. Input accepts DC-coupled differential signals as small as 100mV (200mVpp). Each pin of this pair internally terminates with 50Ω to the VT pin. If the input swing falls below a certain threshold (typical 30mV), the Fail Safe Input (FSI) feature will guarantee a stable output by latching the output to its last valid state. See "Input Interface Applications" subsection.
2	VT	Input Termination Center-Tap: Each input terminates to this pin. The V_T pin provides a center-tap for each input (IN, /IN) to a termination network for maximum interface flexibility. See "Input Interface Applications" subsection.
4	VREF-AC	Reference Voltage: This output biases to V_{CC}–1.2V. It is used for AC-coupling inputs IN and /IN. Connect VREF-AC directly to the corresponding VT pin. Bypass with 0.01µF low ESR capacitor to VCC. Maximum sink/source current is ±1.5mA. See "Input Interface Applications" subsection.
5, 8, 13, 16	VCC	Positive Power Supply: Bypass with 0.1uF//0.01uF low ESR capacitors as close to the V_{CC} pins as possible.
6, 7, 14, 15	GND, Exposed pad	Ground: Exposed pad must be connected to a ground plane that is the same potential as the ground pins.
9, 10 11, 12	/Q1, Q1 /Q0, Q0	LVPECL Differential Output Pairs: Differential buffered copies of the input signal. The output swing is typically 800mV. Unused output pair may be left floating with no impact on jitter. See "LVPECL Output Termination" subsection.

Absolute Maximum Ratings[1]

Supply Voltage (V_{CC}) .... –0.5V to +4.0V
Input Voltage (V_{IN}) .... –0.5V to V_{CC}
LVPECL Output Current(I_{OUT})
    Continuous.. 50mA
    Surge 100mA
Current (V_T)
    Source or sink on VT pin .... ±100mA
Input Current
    Source or sink Current on (IN, /IN) .... ±50mA
Current (V_{REF})
    Source or sink current on V_{REF-AC}[4] .... ±1.5mA
Maximum operating Junction Temperature .... 125°C
Lead Temperature (soldering, 20sec.) .... 260°C
Storage Temperature (T_s) .... –65°C to +150°C

Operating Ratings[2]

Supply Voltage (V_{IN}) .... +2.375V to +3.60V
Ambient Temperature (T_A) .... –40°C to +85°C
Package Thermal Resistance[3]
  QFN
     Still-air (θ_{JA}) .... 60°C/W
     Junction-to-board (ψ_{JB}) .... 33°C/W

DC Electrical Characteristics[5]

T_A = –40°C to +85°C, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{CC}	Power Supply Voltage Range		2.375 3.0	2.5 3.3	2.625 3.6	V
I_{CC}	Power Supply Current	No load, max. V_{CC}		40	60	mA
R_{DIFF_IN}	Differential Input Resistance (IN-to-/IN)		90	100	110	Ω
V_{IH}	Input HIGH Voltage (IN, /IN)	IN, /IN, Note 7	V_{CC}–1.6		V_{CC}	V
V_{IL}	Input LOW Voltage (IN, /IN)	IN, /IN	0		V_{IH}–0.1	V
V_{IN}	Input Voltage Swing (IN, /IN)	see Figure 3a, Note 6	0.1		1.7	V
V_{DIFF_IN}	Differential Input Voltage Swing (|IN - /IN|)	see Figure 3b	0.2			V
V_{IN_FSI}	Input Voltage Threshold that Triggers FSI			30	100	mV
V_{REF-AC}	Output Reference Voltage		V_{CC}–1.3	V_{CC}–1.2	V_{CC}–1.1	V
IN to V_T					1.28	V

Notes:

1. Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.

2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.

3. Package thermal resistance assumes exposed pad is soldered (or equivalent) to the device's most negative potential on the PCB. ψ_{JB} and θ_{JA} values are determined for a 4-layer board in still-air number, unless otherwise stated.

4. Due to the limited drive capability, use for input of the same package only.

5. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

6. V_{IN} (max) is specified when V_T is floating.

7. V_{IH} (min) not lower than 1.2V.

LVPECL Outputs DC Electrical Characteristics[7]

V_{CC} = +2.5V ±5% or +3.3V ±10%, R_L = 50Ω to V_{CC}-2V; T_A = –40°C to +85°C, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{OH}	Output HIGH Voltage	Q0, /Q0, Q1, /Q1	V_{CC}-1.145		V_{CC} -0.895	V
V_{OL}	Output LOW Voltage	Q0, /Q0, Q1, /Q1	V_{CC}-1.945		V_{CC}-1.695	V
V_{OUT}	Output Voltage Swing	See Figure 3a	550	800	950	mV
V_{DIFF_OUT}	Differential Output Voltage Swing	See Figure 3b	1100	1600		mV

Notes:

7. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

AC Electrical Characteristics

V_{CC} = +2.5V ±5% or +3.3V ±10%, R_L = 50Ω to V_{CC}-2V, Input t_r/t_f: ≤300ps; T_A = −40°C to +85°C, unless otherwise stated.

Symbol	Parameter		Condition		Min	Typ	Max	Units
f_{MAX}	Maximum Frequency		NRZ Data		3.2	4.25		Gbps
			V_{OUT} > 400mV	Clock	2.5	3		GHz
t_{PD}	Propagation Delay	IN-to-Q	V_{IN}: 100mV-200mV		180	300	450	ps
			V_{IN}: 200mV-800mV		150	230	350	ps
t_{Skew}	Within Device Skew		Note 8			4	20	ps
	Part-to-Part Skew		Note 9				135	ps
t_{Jitter}	Data	Random Jitter	Note 10				1	ps_{RMS}
		Deterministic Jitter	Note 12				10	ps_{PP}
	Clock	Cycle-to-Cycle Jitter	Note 13				1	ps_{RMS}
		Total Jitter	Note 13				10	ps_{PP}
t_r, t_f	Output Rise/Fall Time (20% to 80%)		At full output swing.		40	75	110	ps
	Duty Cycle		Differential I/O		47		53	%

Notes:

8. Within device skew is measured between two different outputs under identical input transitions.

9. Part-to-part skew is defined for two parts with identical power supply voltages at the same temperature and no skew at the edges at the respective inputs.

10. Random jitter is measured with a K28.7 pattern, measured at ≤ f_{MAX}.

11. Deterministic jitter is measured at 2.5Gbps with both K28.5 and 2^{23}–1 PRBS pattern.

12. Cycle-to-cycle jitter definition: the variation period between adjacent cycles over a random sample of adjacent cycle pairs. $t_{JITTER\_CC} = T_n − T_{n+1}$, where T is the time between rising edges of the output signal.

13. Total jitter definition: with an ideal clock input frequency of ≤ f_{MAX} (device), no more than one output edge in 10^{12} output edges will deviate by more than the specified peak-to-peak jitter value.

Functional Description

Fail-Safe Input (FSI)

The input includes a special failsafe circuit to sense the amplitude of the input signal and to latch the outputs when there is no input signal present, or when the amplitude of the input signal drops sufficiently below $100mV_{PK}$ ($200mV_{PP}$), typically $30mV_{PK}$. Maximum frequency of SY58607U is limited by the FSI function.

Input Clock Failure Case

If the input clock fails to a floating, static, or extremely low signal swing, the FSI function will eliminate a metastable condition and guarantee a stable output. No ringing and no undetermined state will occur at the output under these conditions.

Note that the FSI function will not prevent duty cycle distortion in case of a slowly deteriorating (but still toggling) input signal. Due to the FSI function, the propagation delay will depend on rise and fall time of the input signal and on its amplitude. Refer to "Typical Characteristics" for detailed information.

Timing Diagrams
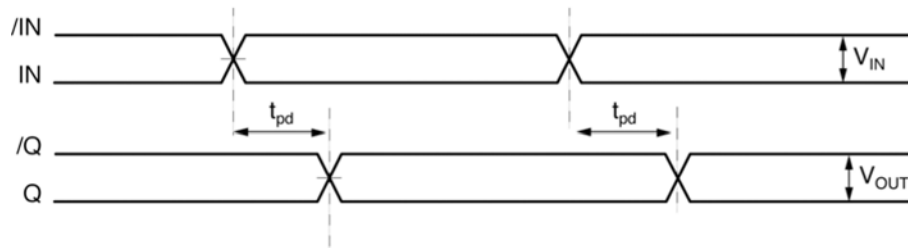
Figure 1a. Propagation Delay
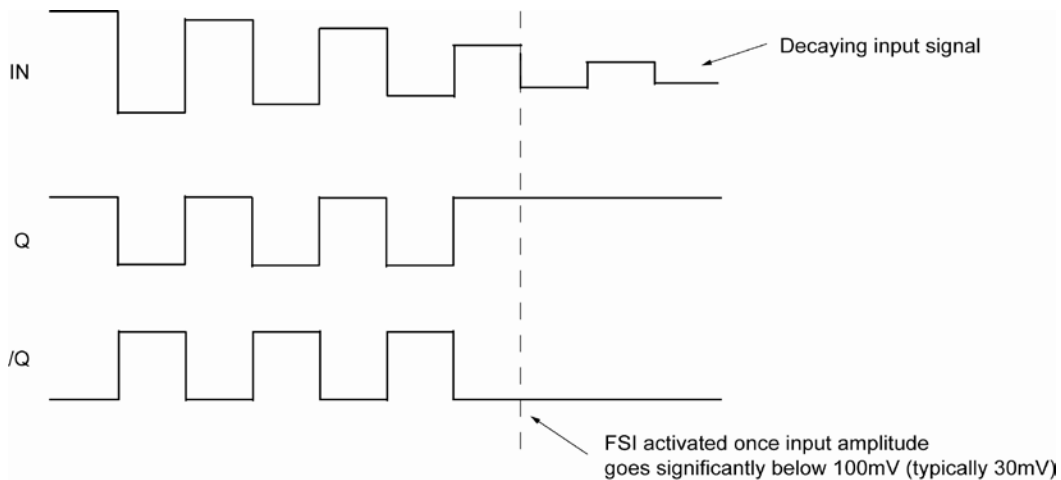
Figure 1b. Fail Safe Feature

Typical Characteristics

V_{CC} = 3.3V, GND = 0V, V_{IN} = 100mV, R_L = 50Ω to V_{CC}-2V, T_A = 25°C, unless otherwise stated.

Frequency Response

Propagation Delay vs. Input Rise/Fall Time
V_{IN} = 100mV

Propagation Delay vs. Input Rise/Fall Time
V_{IN} = 200mV

Propagation Delay vs. Input Rise/Fall Time
V_{IN} = 400mV

Propagation Delay vs. Input Rise/Fall Time
V_{IN} = 800mV
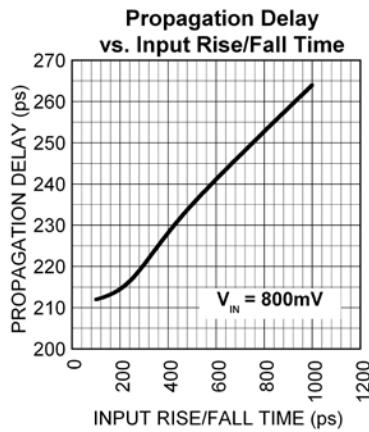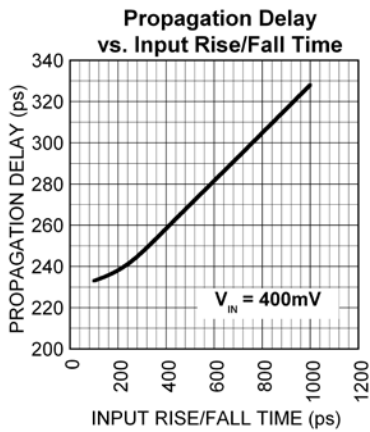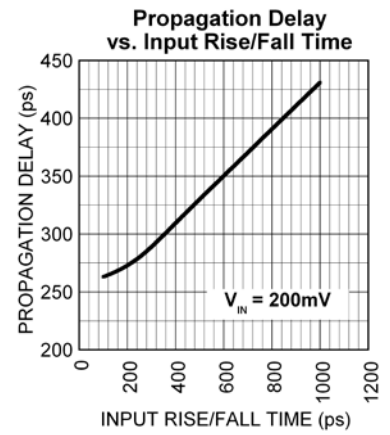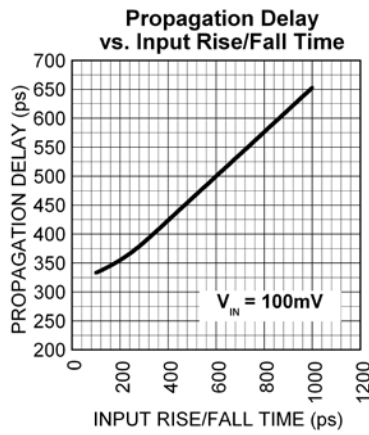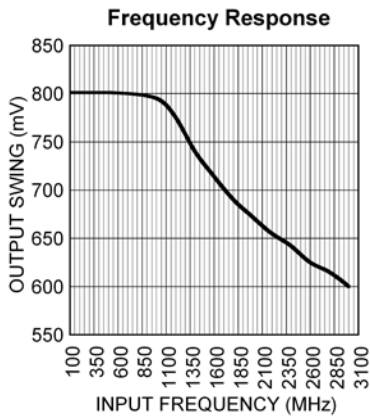
Functional Characteristics

V_{CC} = 3.3V, GND = 0V, V_{IN} = 400mV, Data Pattern: 2^{23}-1, R_L = 50Ω to V_{CC}-2V, T_A = 25°C, unless otherwise stated.
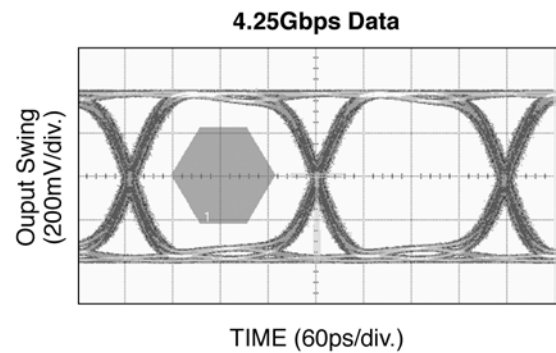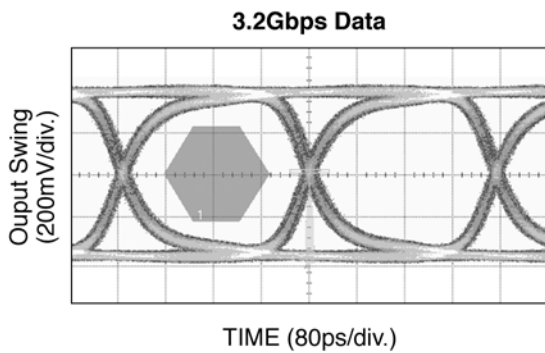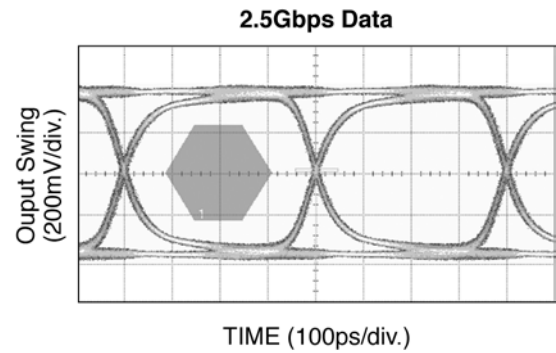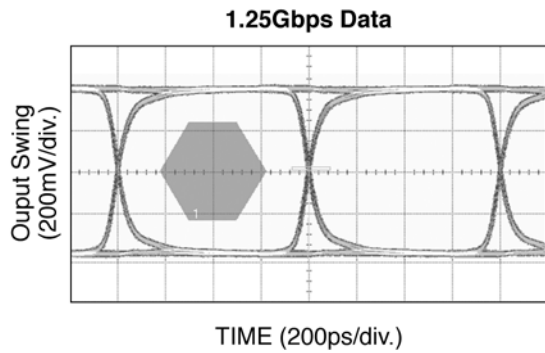
Functional Characteristics (continued)

V_{CC} = 3.3V, GND = 0V, V_{IN} = 400mV, R_L = 50Ω to V_{CC}-2V, T_A = 25°C, unless otherwise stated.

625MHz Clock

Output Swing (200mV/div.)

TIME (200ps/div.)

1.25GHz Clock

Output Swing (200mV/div.)

TIME (100ps/div.)

2GHz Clock

Output Swing (200mV/div.)

TIME (100ps/div.)

3GHz Clock

Output Swing (200mV/div.)

TIME (50ps/div.)
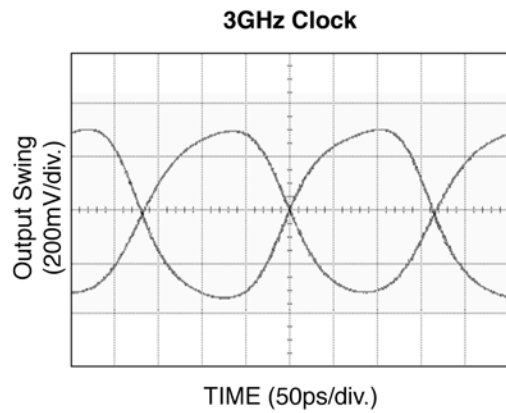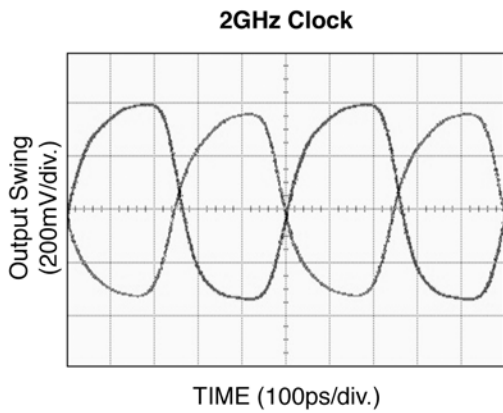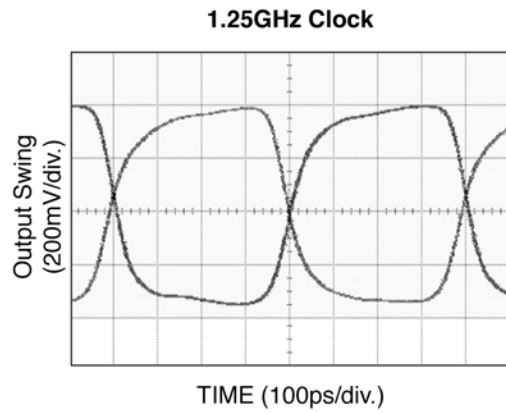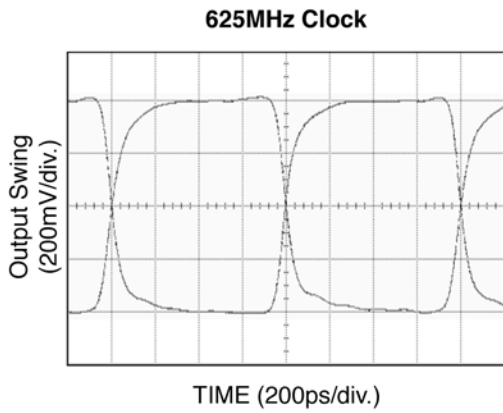
Input and Output Stage

Figure 2a. Simplified Differential Input Buffer
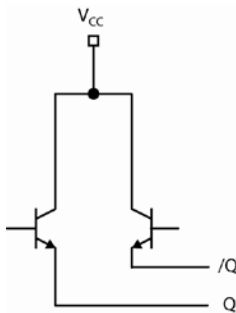
Figure 2b. Simplified LVPECL Output Buffer

Single-Ended and Differential Swings
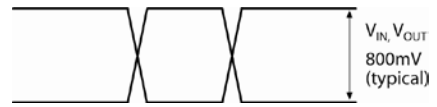
Figure 3a. Single-Ended Voltage Swing
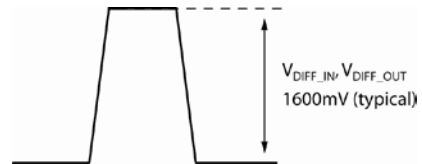
Figure 3b. Differential Voltage Swing
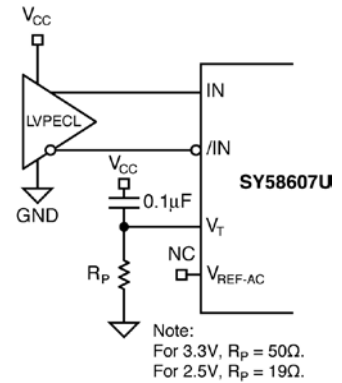
Input Interface Applications
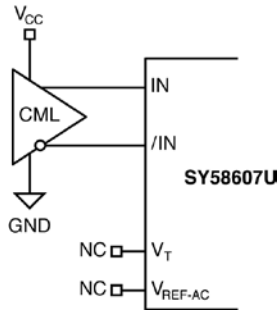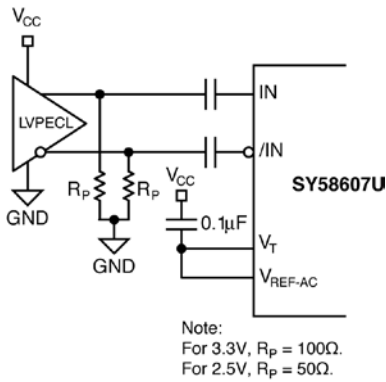

Figure 4a. CML Interface (DC-Coupled)
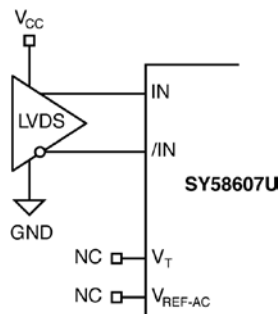
Option: May connect V_T to V_{CC}
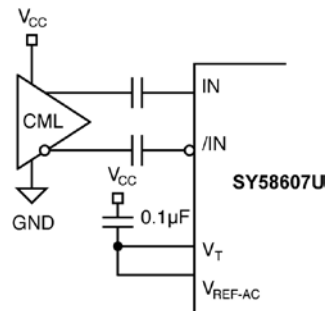
Figure 4b. CML Interface (AC-Coupled)

Figure 4c. LVPECL Interface (DC-Coupled)

Figure 4d. LVPECL Interface (AC-Coupled)

Figure 4e. LVDS Interface

LVPECL Output Termination

LVPECL outputs have very low output impedance (open emitter), and small signal swing which results in low EMI. LVECL is ideal for driving 50Ω- and 100Ω-controlled impedance transmission lines. There are several techniques in terminating the LVPECL output, as shown in Figures 5a through 5c.
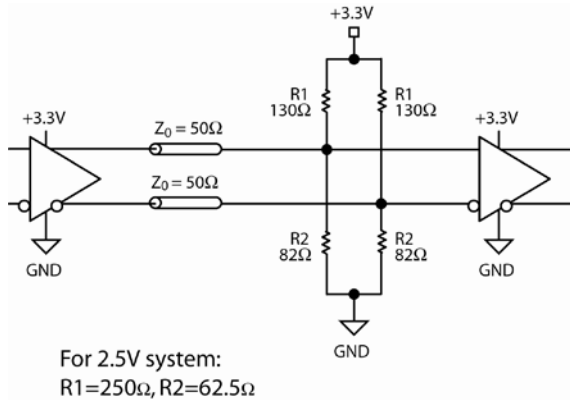

For 2.5V system:
R1=250Ω, R2=62.5Ω

Figure 5a. Parallel Termination-Thevenin Equivalent

For 2.5V system:
R1=19Ω

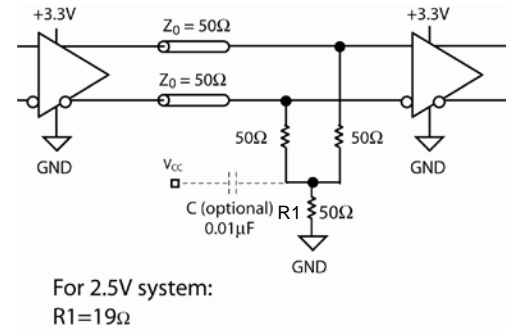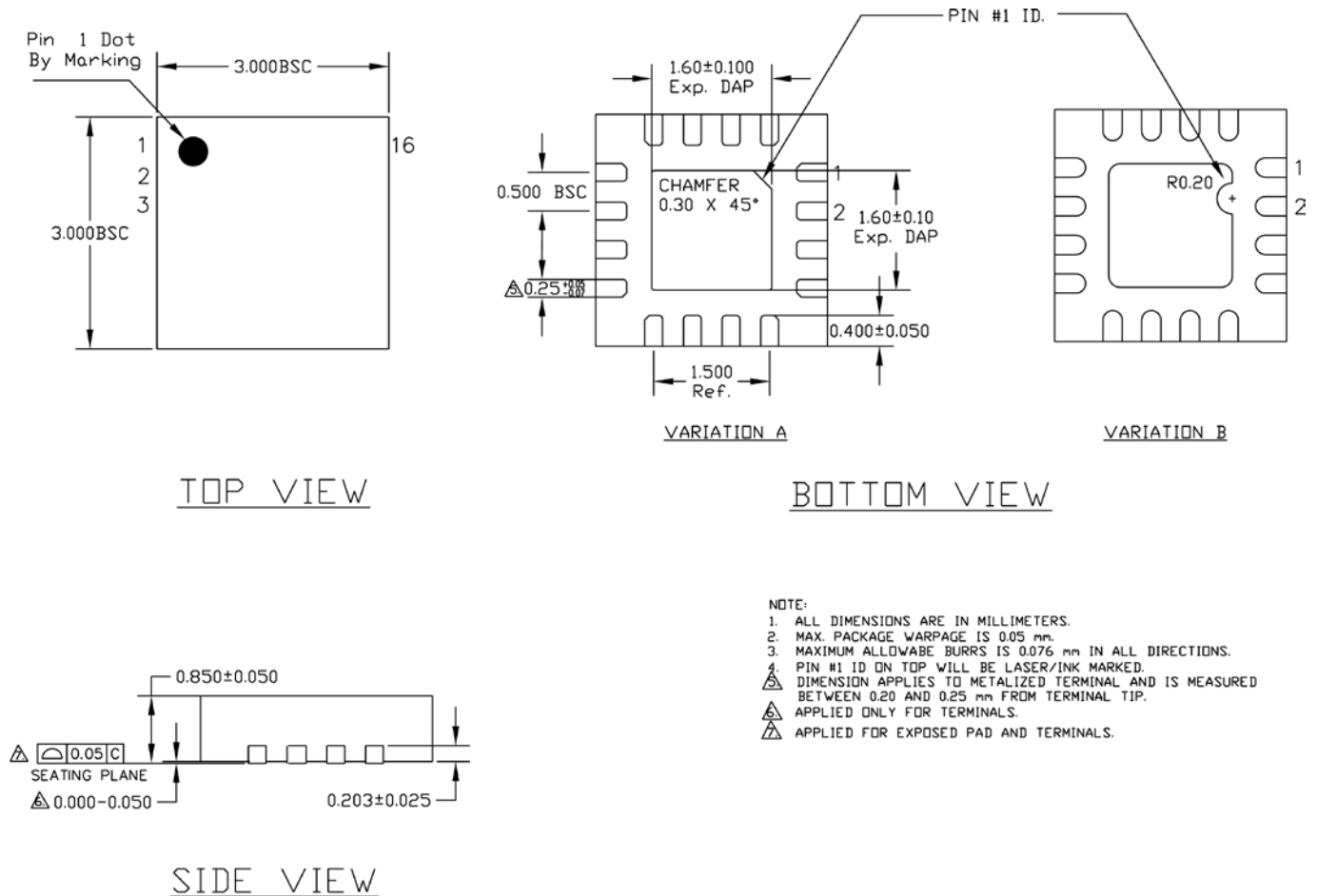**Figure 5b. Three-Resistor "Y-Termination"**

Related Product and Support Documents

Part Number	Function	Data Sheet Link
SY58606U	4.25Gbps Precision, 1:2 CML Fanout Buffer with Internal Termination and Fail Safe Input	http://www.micrel.com/page.do?page=/product-info/products/sy58606u.shtml
SY58608U	3.2Gbps Precision, 1:2 LVDS Fanout Buffer Buffer with Internal Termination and Fail Safe Input	http://www.micrel.com/page.do?page=/product-info/products/sy58608u.shtml
HBW Solutions	New Products and Termination Application Notes	http://www.micrel.com/page.do?page=/product-info/as/HBWsolutions.shtml

Package Information

Pin 1 Dot By Marking

3.000BSC

3.000BSC

TOP VIEW

1.60±0.100 Exp. DAP

PIN #1 ID.

0.500 BSC

CHAMFER 0.30 X 45°

0.25

1.500 Ref.

2 1.60±0.10 Exp. DAP

0.400±0.050

VARIATION A

R0.20

VARIATION B

BOTTOM VIEW

NOTE:
1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. MAX. PACKAGE WARPAGE IS 0.05 mm.
3. MAXIMUM ALLOWABE BURRS IS 0.076 mm IN ALL DIRECTIONS.
4. PIN #1 ID ON TOP WILL BE LASER/INK MARKED.
5. DIMENSION APPLIES TO METALIZED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25 mm FROM TERMINAL TIP.
6. APPLIED ONLY FOR TERMINALS.
7. APPLIED FOR EXPOSED PAD AND TERMINALS.

0.850±0.050

0.05 C

SEATING PLANE

0.000-0.050

0.203±0.025

SIDE VIEW

16-Pin QFN

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